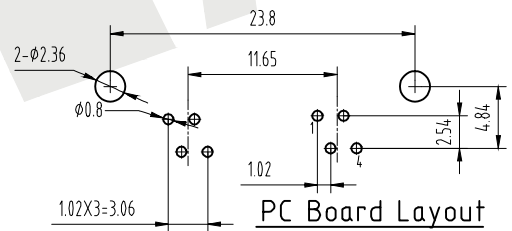
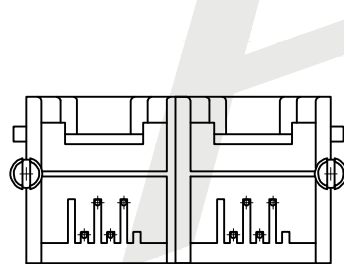
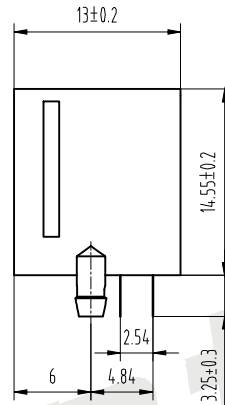
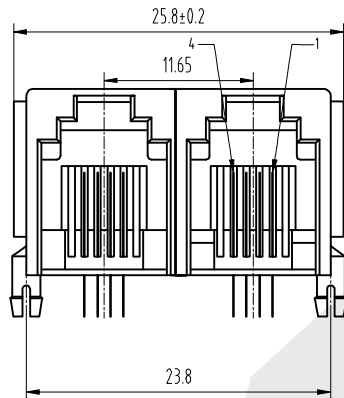


HSF



PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING $1\mu\sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATEI

ELECTRICAL

1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVIROMENTAL

1. STORAGE: -40°C TO 85°C
2. OPERATION: 0°C TO 70°C

Order code:

ATRJ5522 - 6P -4C - X - A - B - A
① ② ③ ④ ⑤ ⑥ ⑦

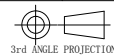
- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact Plating
G0: Gold flash
G1: 3U" Gold
G2: 5U" Gold
G3: 10U" Gold
G4: 15U" Gold
G5: 30U" Gold
SN: Tin
- ⑤ Shield
A: W/O Shield
B: Half Shield
C: Shield W/Eml
D: Shield W/O Eml
- ⑥ Ports
A: 1X1P
B: 1X2P
C: 1X4P
D: 1X5P
E: 1X6P
F: 1X8P
- ⑦ With Panel or not
A: With panel
B: Without panel

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm

DRAW Wu Feng Rong DATE 07/09/2019

CHECK BobYang DATE 07/09/2019



ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE: RJ11 Jack side entry,
Full Plastic with panel, 1X2P

DRAWING NO: ATRJ5522-6P4C-X-A-B-A

PRODUCT NO: ATRJ5522-6P4C-X-A-B-A

D

D

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		
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8		